



Form PTO-1449

Applicant: Tanspuz, et al.

Serial No.: 10/678,010

Filing Date: October 2, 2003

For: METHOD FOR MAINTAINING SOLDER THICKNESS
IN FLIPCHIP ATTACH PACKAGING PROCESS

Sheet 1 of 1

Att'y Docket No. 11948.36

Group: 2828

2818

INFORMATION DISCLOSURE CITATIONS MADE BY APPLICANTCo-Pending Applications

Examiner Initial*	Application Number	Filing Date
TH A1.	10/413,668	04/14/2003

U.S. Patent Documents

Examiner Initial*	Document Number	Issue Date	Name
TH A2.	6,297,562	10/01/02/2001	Tilly
TH A3.	6,307,755	10/23/2001	Williams, et al.
TH A4.	6,391,758	05/04/21/2002	Lo, et al.
TH A5.	6,720,642	04/13/2004	Joshi, et al.
TH A6.	6,774,466	08/10/2004	Kijiwara, et al.

DOCS-#800206-v1-Supp_IDS_1449.DOC

Examiner: TH TH HO

Date Considered: May 2005

*EXAMINER: Initial if reference considered, whether or not citation is in conformance with MPEP 609; draw line through citation if not in conformance and not considered. Include copy of this form with next communication to applicant.